[WD1] Modeling and Simulation of Plasma-Surface Interaction

Date / Time	July 25 (Wed.), 2018 / 09:00-10:30
Place	Room D (#115)
Session Chair(s)	Hae June Lee (Pusan Nat'l Univ., Korea) Yuan-Hong Song (Dalian Univ. of Tech., China)

WD1-1 [Invited]   09:00-09:30

Realistic Treatment of Plasma-Surface Interactions in Simulations of Low Temperature Plasmas

Julian Schulze[1], Aranka Derzsi[2], Manaswi Daksha[1], Benedek Horvath[3], Birk Berger[4], Ihor Korolov[1], Steven Brandt[2], Mark Koepke[2], Zoltan Donko[3], and Peter Awakowicz[1]

[1]Ruhr-Univ. Bochum, Germany, [2]West Virginia Univ., USA, [3]Hungarian Academy of Sciences, Hungary, [4]Brandenburg Univ. of Tech., Germany

WD1-2 [Invited]   09:30-10:00

Modeling of Plasma-Enhanced ALD for Silicon Oxide Films as Clarification of Fundamental Deposition Mechanism

Kosuke Yamamoto, Ayuta Suzuki, Munehito Kagaya, Hu Li, Masaaki Matsukuma, and Tsuyoshi Moriya
Tokyo Electron Tech. Solutions Ltd., Japan

WD1-3 [Invited]   10:00-10:30

Importance of Consideration of Thermal Diffusion Effects in a Non-Isothermal Capacitively Coupled Plasma Reactor

Ho Jun Kim
Dong-A Univ., Korea